

AP90P03K

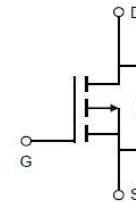
P-Channel Enhancement Mosfet

AIPOWER

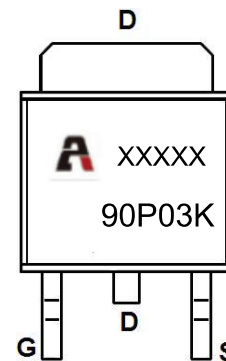
DATA SHEET

Feature

- -30V,-90A
 $R_{DS(ON)} < 7.5m\Omega @ V_{GS} = -10V$ TYP:5.8 m Ω
 $R_{DS(ON)} < 12m\Omega @ V_{GS} = -4.5V$ TYP:9 m Ω
- Advanced Trench Technology
- Lead free product is acquired
- Low Gate Charge
- Excellent Cdv/dt effect decline



Schematic Diagram



Marking and pin assignment

Application

- PWM applications
- Load Switch
- Power management

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
90P03K	AP90P03K	TO-252	13 inch	-	2500

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_a = 25^\circ\text{C}$)	I_D	-90	A
Continuous Drain Current ($T_a = 100^\circ\text{C}$)	I_D	-63	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	-360	A
Single Pulsed Avalanche Energy ⁽²⁾	E_{AS}	135	mJ
Power Dissipation	P_D	79	W
Thermal Resistance from Junction to Case ⁽⁴⁾	$R_{\theta JC}$	2.5	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Ambient ⁽⁴⁾	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

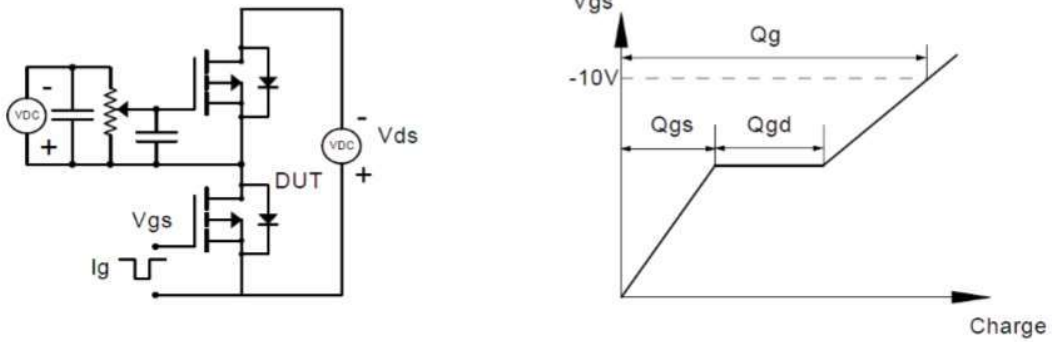
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -30V, V_{GS} = 0V$	-	-	-1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage ⁽³⁾	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
Drain-source on-resistance ⁽³⁾	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -30A$	-	5.8	7.5	m Ω
		$V_{GS} = -4.5V, I_D = -20A$	-	9	12	
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$	-	4320	-	pF
Output Capacitance	C_{oss}		-	534	-	
Reverse Transfer Capacitance	C_{rss}		-	493	-	
Switching characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -15V, I_D = -15A,$ $V_{GS} = -10V, R_G = 2.5\Omega$	-	19	-	ns
Turn-on rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	65	-	
Turn-off fall time	t_f		-	36	-	
Total Gate Charge	Q_g	$V_{DS} = -15V, I_D = -15A,$ $V_{GS} = -10V$	-	45	-	nC
Gate-Source Charge	Q_{gs}		-	8	-	
Gate-Drain Charge	Q_{gd}		-	12	-	
Source-Drain Diode characteristics						
Diode Forward voltage ⁽³⁾	V_{DS}	$V_{GS} = 0V, I_S = -1A$	-	-	-1.2	V
Diode Forward current ⁽⁴⁾	I_S		-	-	-90	A

Notes:

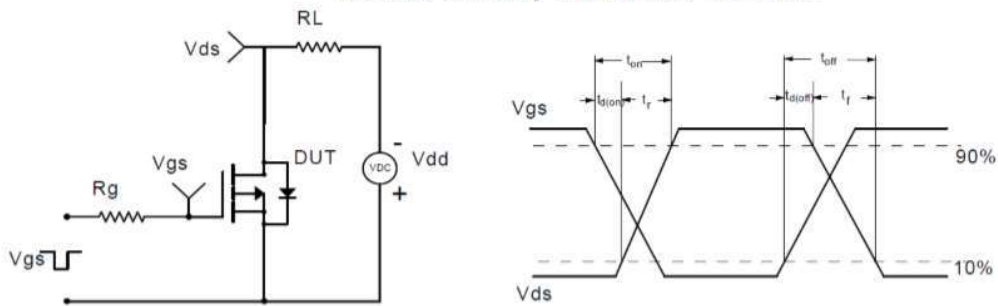
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J = 25^\circ\text{C}, V_{DD} = -15V, R_G = 25\Omega, L = 0.5mH$
3. Pulse Test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board, $t \leq 10$ sec

Test Circuit

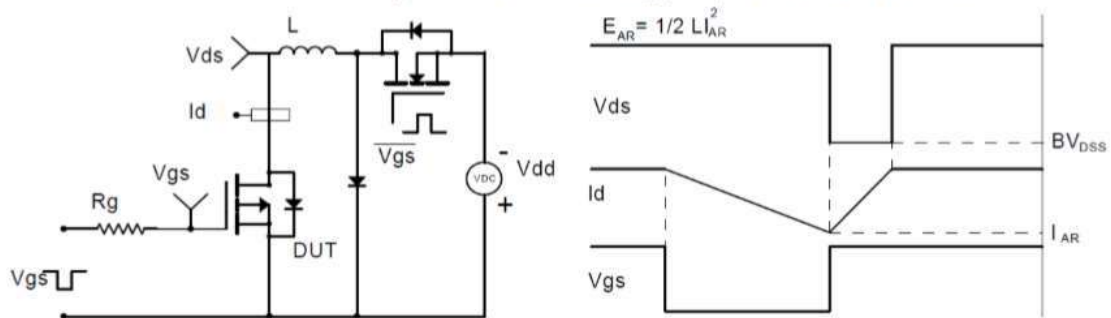
Gate Charge Test Circuit & Waveform



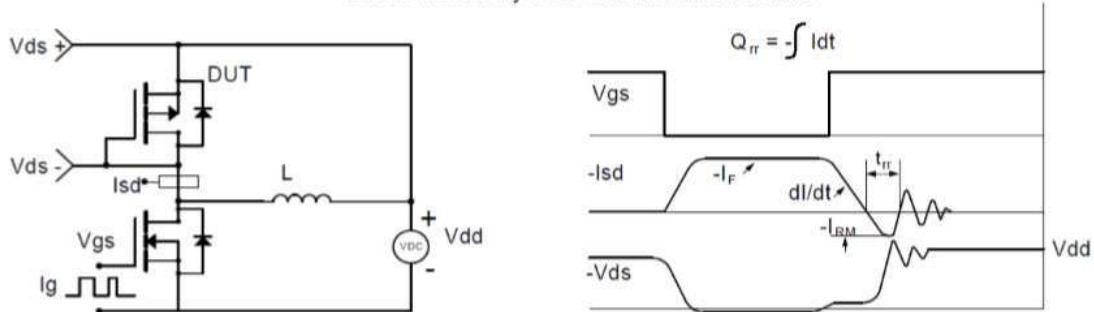
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Typical Performance Characteristics

Figure 1: Output Characteristics

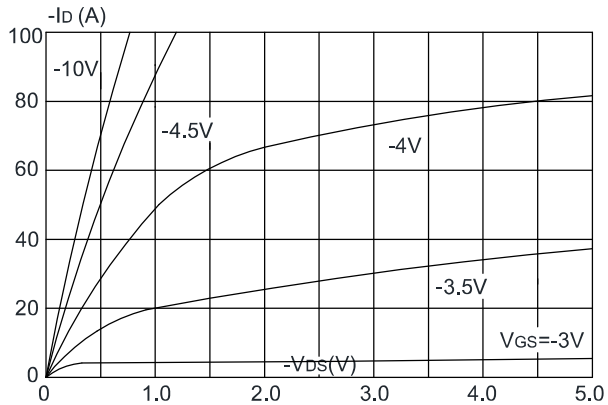


Figure 2: Typical Transfer Characteristics

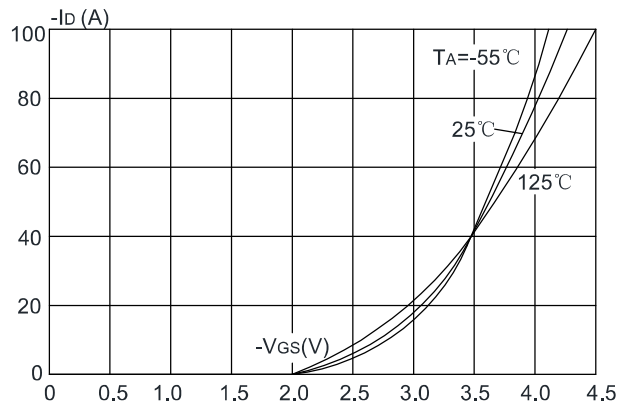


Figure 3: On-resistance vs. Drain Current

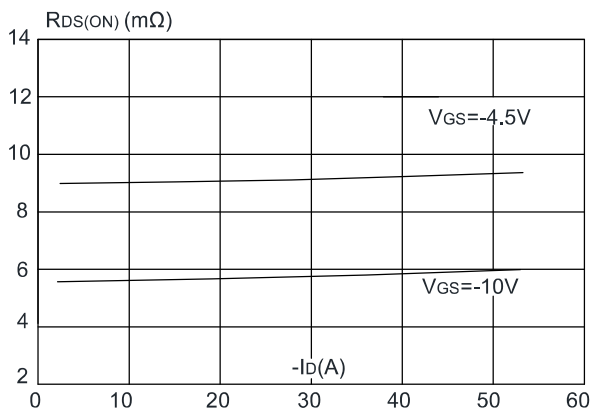


Figure 4: Body Diode Characteristics

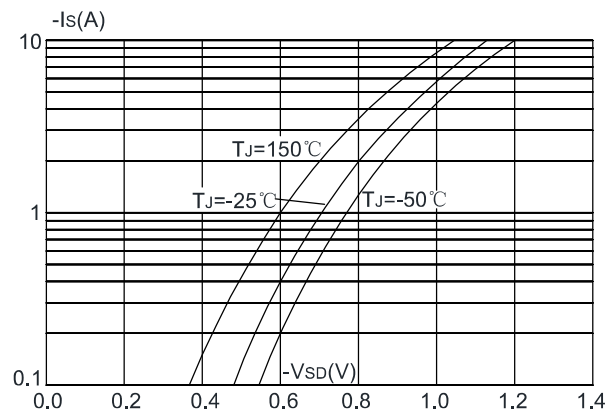


Figure 5: Gate Charge Characteristics

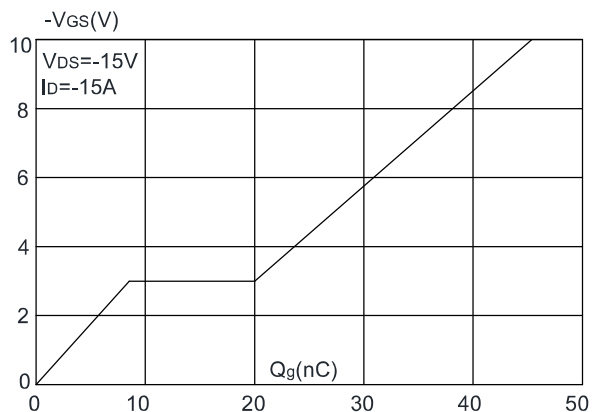


Figure 6: Capacitance Characteristics

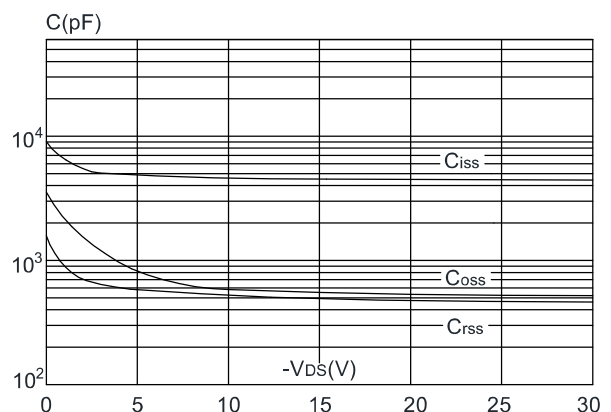


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

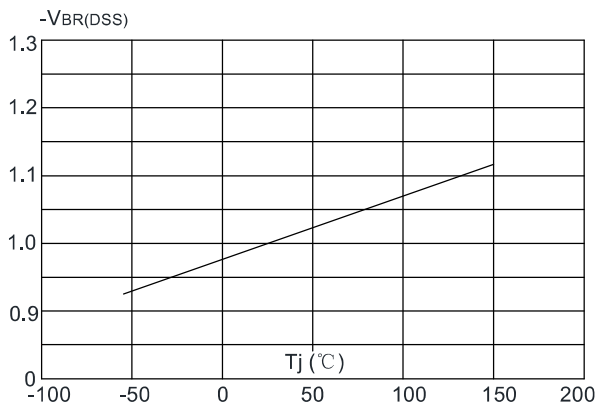


Figure 8: Normalized on Resistance vs. Junction Temperature

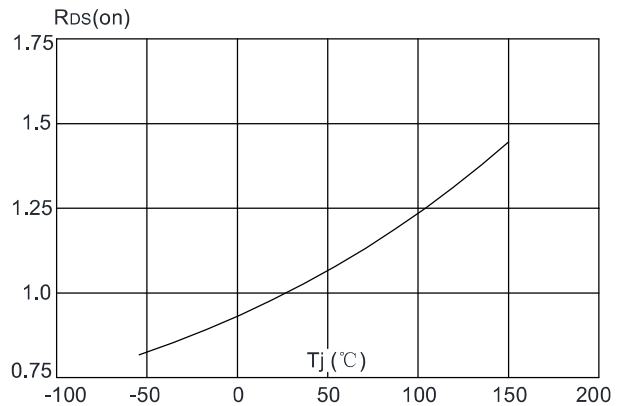


Figure 9: Maximum Safe Operating Area

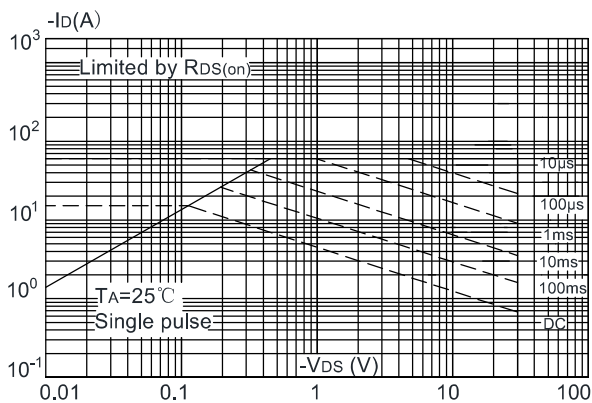


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

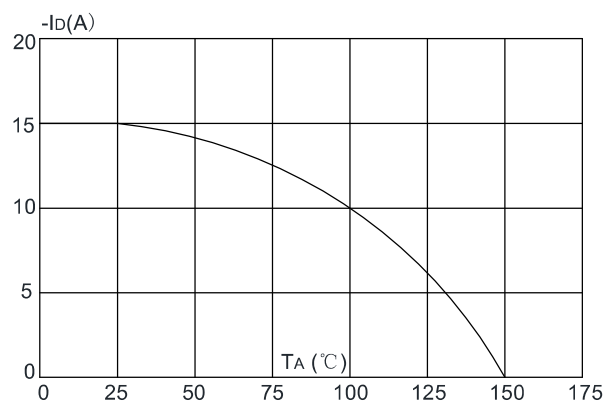
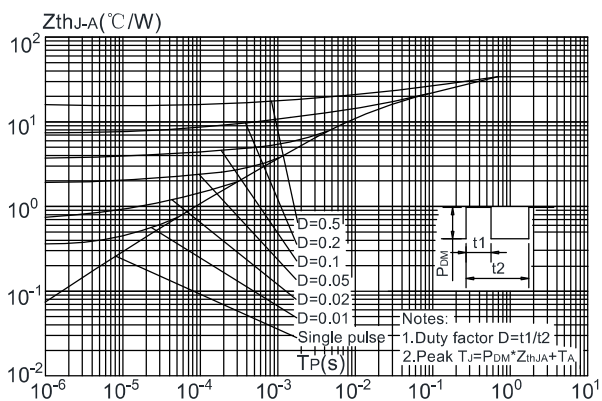


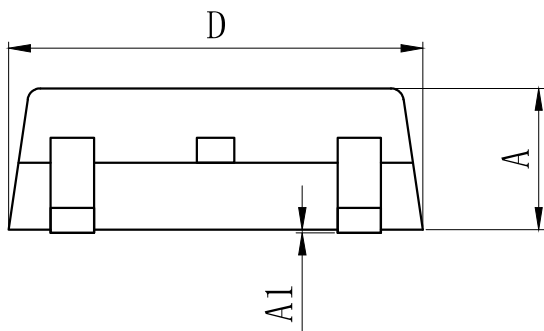
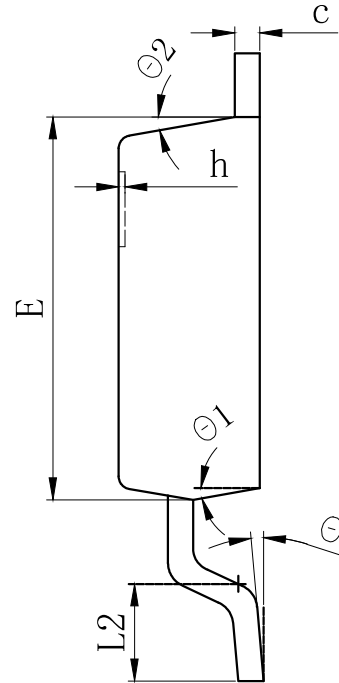
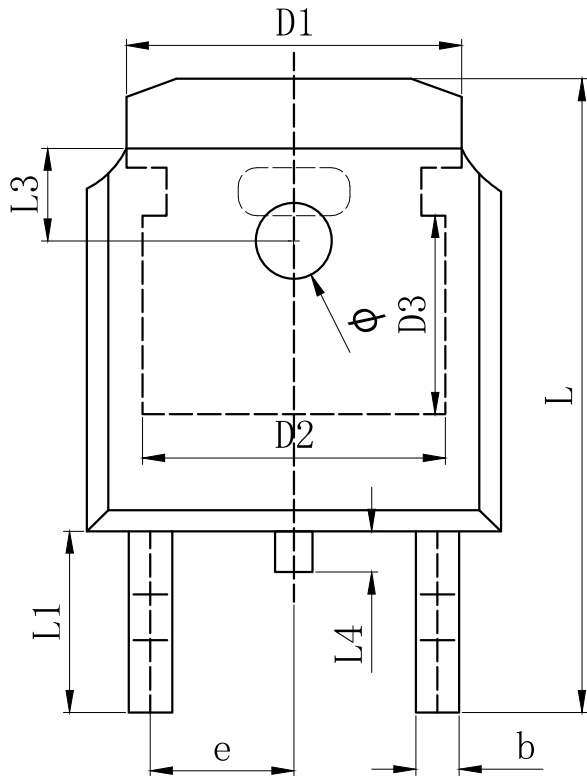
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



AP90P03K

P-Channel Enhancement Mosfet

TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
$\theta 1$	9° TYP		
$\theta 2$	9° TYP		

Revision History

Revision	Release	Remark
V1.1	2022/10/23	Initial Release

Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.